

FEATURES

Tiny 3.35 mm × 2.50 mm × 0.88 mm surface-mount package
High SNR of 62 dBA
High sensitivity of –38 dBV
Flat frequency response from 100 Hz to 15 kHz
Low current consumption: <250 μA
Single-ended analog output
High PSR of 70 dB
Compatible with Sn/Pb and Pb-free solder processes
RoHS/WEEE compliant

APPLICATIONS

Smartphones and feature phones
Teleconferencing systems
Digital video cameras
Bluetooth headsets
Video phones
Tablets

GENERAL DESCRIPTION

The **ADMP404**¹ is a high quality, high performance, low power, analog output bottom-ported omnidirectional MEMS microphone. The **ADMP404** consists of a MEMS microphone element, an impedance converter, and an output amplifier. The **ADMP404** sensitivity specification makes it an excellent choice for both near field and far field applications. The **ADMP404** has a high signal-to-noise ratio (SNR) and flat, wideband frequency response, resulting in natural sound with high intelligibility. Its low current consumption enables long battery life for portable applications.

FUNCTIONAL BLOCK DIAGRAM

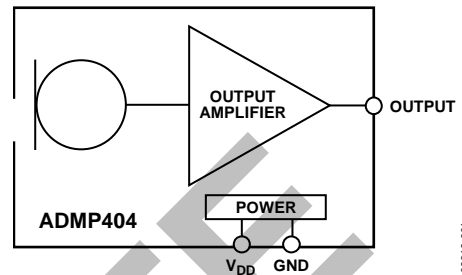


Figure 1.

0861E-001

The **ADMP404** complies with the TIA-920 *Telecommunications Telephone Terminal Equipment Transmission Requirements for Wideband Digital Wireline Telephones* standard.

The **ADMP404** is available in an ultraminiature 3.35 mm × 2.50 mm × 0.88 mm surface-mount package. It is reflow solder compatible with no sensitivity degradation. The **ADMP404** is halide free.

¹ Protected by U.S. Patents 7,449,356; 7,825,484; 7,885,423; 7,961,897. Other patents are pending.

Rev. C

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REVISION HISTORY

7/12—Rev. B to Rev. C

Changes to Features Section, General Description Section, Figure 1, and Page 1 Layout.....	1
Add Note 1.....	1
Changes to Powers Supply Rejection Parameter, Table 1.....	3
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Changes to Connecting to Analog Devices Audio Codecs Section, Figure 8, and Application Notes Section	7
Added Circuit Notes Section.....	7
Changes to Temperature Humidity Bias (THB) Description Column, Table 5 and Temperature Cycle Column, Table 5.....	10
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Deleted Figure 12.....	11

8/11—Rev. A to Rev. B

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Changes to Supply Voltage Parameter, Table 1.....	3
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Added Connecting to Analog Devices, Inc., Audio Codecs Section and Supporting Documents Section.....	7
Changes to Pick and Place Equipment Section (20 kg to 10 kg)	9
Added LGA_CAV Tape and Reel Outline Dimensions, Figure 12.....	11

12/10—Rev. 0 to Rev. A

Changes to Applications Section and General Description Section.....	1
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7/10—Revision 0: Initial Version

SPECIFICATIONS

$T_A = 25^\circ\text{C}$, $V_{DD} = 1.8\text{ V}$, unless otherwise noted. All minimum and maximum specifications are guaranteed. Typical specifications are not guaranteed.

Table 1.

Parameter	Symbol	Test Conditions/Comments	Min	Typ	Max	Unit
PERFORMANCE						
Directionality				Omni		
Sensitivity		1 kHz, 94 dB SPL	-41	-38	-35	dBV
Signal-to-Noise Ratio	SNR			62		dB
Equivalent Input Noise	EIN			32		dB
Dynamic Range		Derived from EIN and maximum acoustic input		88		dB
Frequency Response ¹		Low frequency -3 dB point		100		Hz
		High frequency -3 dB point		15		kHz
		Deviation limits from flat response within pass band		-3/+2		dB
Total Harmonic Distortion	THD	105 dB SPL			3	%
Power Supply Rejection	PSR	217 Hz, 100 mV p-p square wave superimposed on $V_{DD} = 1.8\text{ V}$		70		dB
Maximum Acoustic Input		Peak		120		dB SPL
POWER SUPPLY						
Supply Voltage	V_{DD}		1.5		3.3	V
Supply Current	I_S				250	μA
OUTPUT CHARACTERISTICS						
Output Impedance	Z_{OUT}			200		Ω
Output DC Offset				0.8		V
Output Current Limit				90		μA

¹ See Figure 4 and Figure 6.

ABSOLUTE MAXIMUM RATINGS

Table 2.

Parameter	Rating
Supply Voltage	-0.3 V to +3.6 V
Sound Pressure Level (SPL)	160 dB
Mechanical Shock	10,000 g
Vibration	Per MIL-STD-883 Method 2007, Test Condition B
Temperature Range	-40°C to +85°C

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

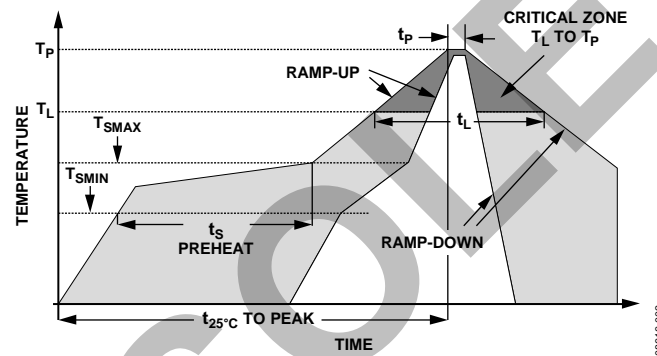
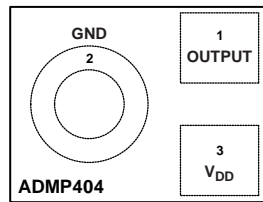


Figure 2. Recommended Soldering Profile Limits

Table 3. Recommended Soldering Profile Limits

Profile Feature	Sn63/Pb37	Pb-Free
Average Ramp Rate (T_L to T_P)	125°C/sec maximum	125°C/sec maximum
Preheat		
Minimum Temperature (T_{SMIN})	100°C	100°C
Maximum Temperature (T_{SMAX})	150°C	200°C
Time (T_{SMIN} to T_{SMAX}), t_s	60 sec to 75 sec	60 sec to 75 sec
Ramp-Up Rate (T_{SMAX} to T_L)	125°C/sec	125°C/sec
Time Maintained Above Liquidous (t_L)	45 sec to 75 sec	~50 sec
Liquidous Temperature (T_L)	183°C	217°C
Peak Temperature (T_P)	215°C +3°C/-3°C	245°C 0°C/-5°C
Time Within 5°C of Actual Peak Temperature (t_P)	20 sec to 30 sec	20 sec to 30 sec
Ramp-Down Rate	3°C/sec maximum	3°C/sec maximum
Time 25°C ($t_{25°C}$) to Peak Temperature	5 minute maximum	5 minute maximum

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS



TOP VIEW
(TERMINAL SIDE DOWN)
Not to Scale

08616-003

Figure 3. Pin Configuration

Table 4. Pin Function Descriptions

Pin No.	Mnemonic	Description
1	OUTPUT	Analog Output Signal
2	GND	Ground
3	V _{DD}	Power Supply

TYPICAL PERFORMANCE CHARACTERISTICS

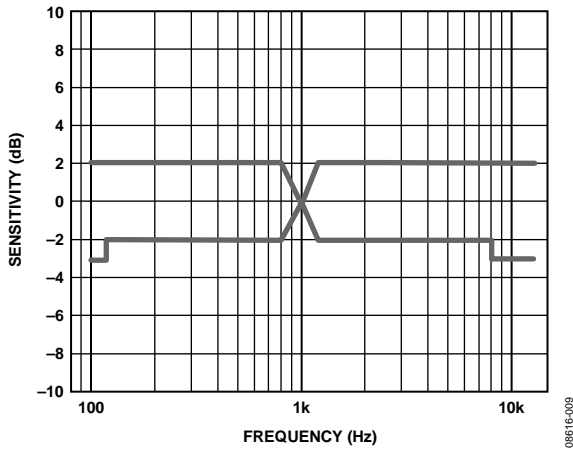


Figure 4. Frequency Response Mask

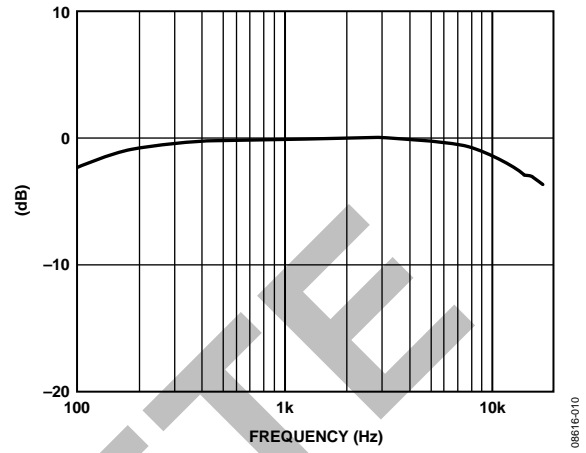


Figure 6. Typical Frequency Response (Measured)

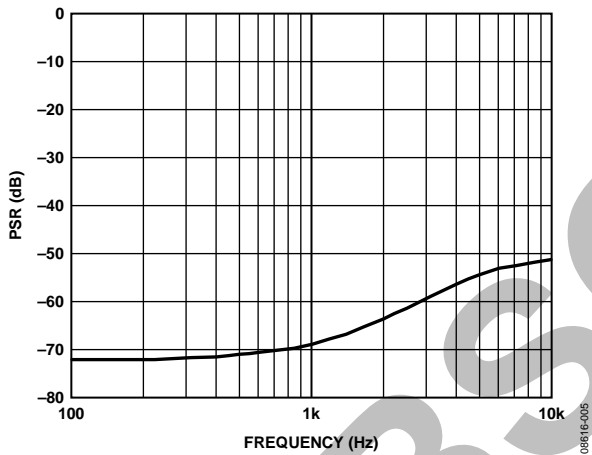


Figure 5. Typical Power Supply Rejection Ratio vs. Frequency

APPLICATIONS INFORMATION

CONNECTING TO ANALOG DEVICES AUDIO CODECS

The **ADMP404** output can be connected to a dedicated codec microphone input (see Figure 7) or to a high input impedance gain stage (see Figure 8). A 0.1 μF ceramic capacitor placed close to the **ADMP404** supply pin is used for testing and is recommended to adequately decouple the microphone from noise on the power supply. A dc-blocking capacitor is required at the output of the microphone. This capacitor creates a high-pass filter with a corner frequency at

$$f_c = 1/(2\pi \times C \times R)$$

where R is the input impedance of the codec.

A minimum value of 2.2 μF is recommended in Figure 7 because the input impedance of the **ADAU1361/ADAU1761** can be as low as 2 k Ω at its highest PGA gain setting, which results in a high-pass filter corner frequency at about 37 Hz. Figure 8 shows the **ADMP404** connected to the **ADA4897-1** op amp configured as a noninverting preamplifier.

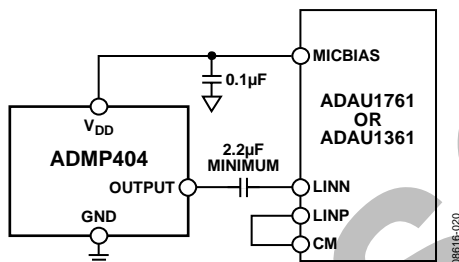


Figure 7. **ADMP404** Connected to the Analog Devices **ADAU1761** or **ADAU1361** Codec

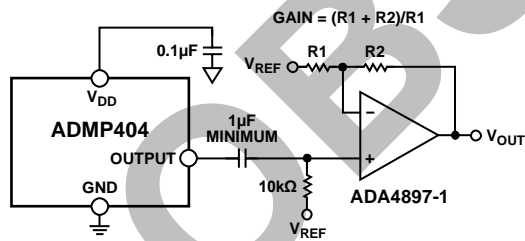


Figure 8. **ADMP404** Connected to the **ADA4897-1** Op Amp

SUPPORTING DOCUMENTS

Evaluation Board User Guide

[UG-142](#), *EVAL-ADMP404Z-FLEX: Bottom-Ported Analog Output MEMS Microphone Evaluation Board*

Application Notes

[AN-1003](#), *Recommendations for Mounting and Connecting Analog Devices, Inc., Bottom-Ported MEMS Microphones*

[AN-1068](#), *Reflow Soldering of the MEMS Microphone*

[AN-1112](#), *Microphone Specifications Explained*

[AN-1124](#), *Recommendations for Sealing Analog Devices, Inc., Bottom-Port MEMS Microphones from Dust and Liquid Ingress*

[AN-1140](#), *Microphone Array Beamforming*

Circuit Notes

[CN-0207](#), *High Performance Analog MEMS Microphone's Simple Interface to SigmaDSP Audio Codec*

[CN-0262](#), *Low Noise Analog MEMS Microphone and Preamp with Compression and Noise Gating*

PCB LAND PATTERN LAYOUT

The recommended PCB land pattern for the ADMP404 should be laid out to a 1:1 ratio to the solder pads on the microphone package, as shown in Figure 9. Take care to avoid applying solder paste to the sound hole in the PCB. A suggested solder

paste stencil pattern layout is shown in Figure 10. The diameter of the sound hole in the PCB should be larger than the diameter of the sound port of the microphone. A minimum diameter of 0.5 mm is recommended.

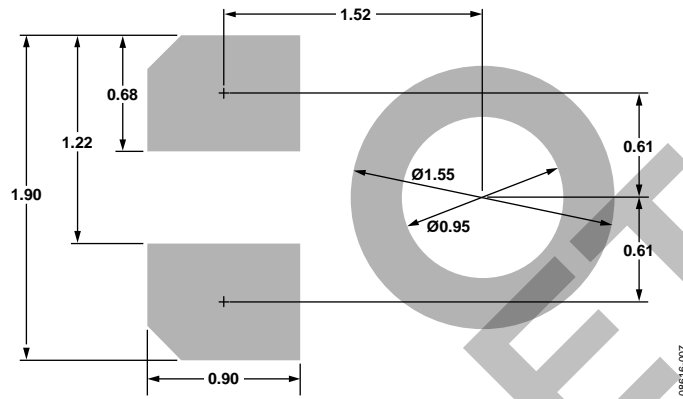


Figure 9. PCB Land Pattern Layout

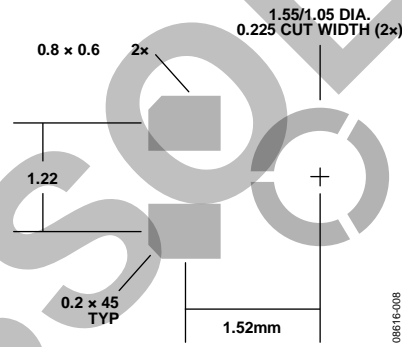


Figure 10. Suggested Solder Paste Stencil Pattern Layout

HANDLING INSTRUCTIONS

PICK AND PLACE EQUIPMENT

The MEMS microphone can be handled using standard pick-and-place and chip shooting equipment. Care should be taken to avoid damage to the MEMS microphone structure as follows:

- Use a standard pickup tool to handle the microphone. Because the microphone hole is on the bottom of the package, the pickup tool can make contact with any part of the lid surface.
- Use care during pick-and-place to ensure that no high shock events above 10 kg are experienced because such events may cause damage to the microphone.
- Do not pick up the microphone with a vacuum tool that makes contact with the bottom side of the microphone. Do not pull air out of or blow air into the microphone port.
- Do not use excessive force to place the microphone on the PCB.

REFLOW SOLDER

For best results, the soldering profile should be in accordance with the recommendations of the manufacturer of the solder paste used to attach the MEMS microphone to the PCB. It is recommended that the solder reflow profile not exceed the limit conditions specified in Figure 2 and Table 3.

BOARD WASH

When washing the PCB, ensure that water does not make contact with the microphone port. Blow-off procedures and ultrasonic cleaning must not be used.

OBSOLETE

RELIABILITY SPECIFICATIONS

The microphone sensitivity after stress must deviate by no more than ± 3 dB from the initial value.

Table 5.

Stress Test	Description
Low Temperature Operating Life	-40°C, 500 hours, powered
High Temperature Operating Life	+125°C, 500 hours, powered
Temperature Humidity Bias (THB)	+85°C/85% relative humidity (RH), 500 hours, powered
Temperature Cycle	-40°C/+125°C, one cycle per hour, 1000 cycles
High Temperature Storage	+150°C, 500 hours
Low Temperature Storage	-40°C, 500 hours
Component CDM ESD	All pins, 0.5 kV
Component HBM ESD	All pins, 1.5 kV
Component MM ESD	All pins, 0.2 kV

OBSOLETE

OUTLINE DIMENSIONS

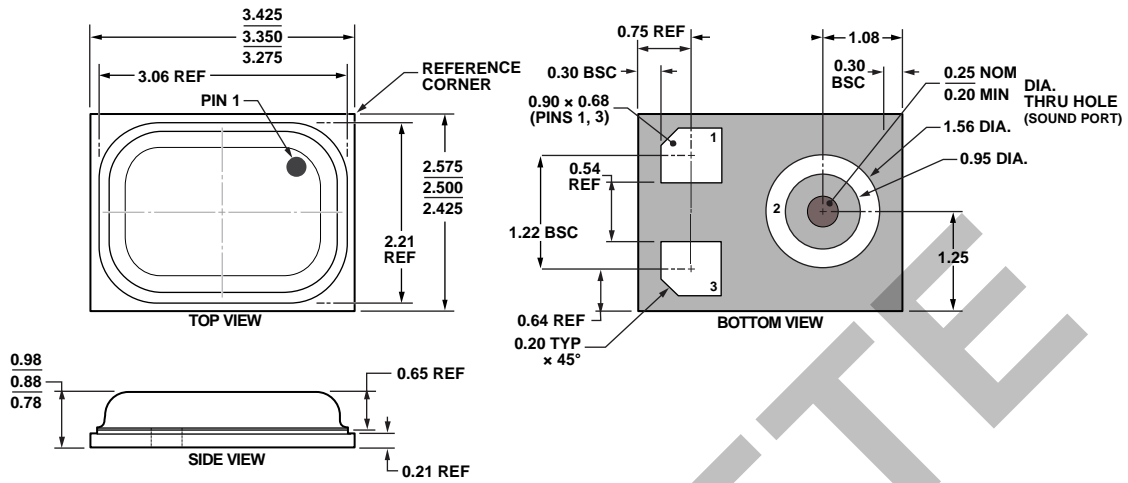


Figure 11. 3-Terminal Chip Array Small Outline No Lead Cavity [LGA_CAV]
 3.35 mm x 2.50 mm Body
 (CE-3-2)
 Dimensions shown in millimeters

06-16-2010-A

ORDERING GUIDE

Model ¹	Temperature Range	Package Description	Package Option ²	Ordering Quantity
ADMP404ACEZ-RL	-40°C to +85°C	3-Terminal LGA_CAV, 13" Tape and Reel	CE-3-2	10,000
ADMP404ACEZ-RL7	-40°C to +85°C	3-Terminal LGA_CAV, 7" Tape and Reel	CE-3-2	1,000
EVAL-ADMP404Z-FLEX		Evaluation Board		

¹ Z = RoHS Compliant Part.

² This package option is halide free.

NOTES

OBSOLETE